

# NCV8570

## 200 mA, Ultra Low Noise, High PSRR, BiCMOS RF LDO Regulator

Noise sensitive RF applications such as Power Amplifiers in satellite radios, infotainment equipment, and precision instrumentation for automotive applications require very clean power supplies.

The NCV8570 is 200 mA LDO that provides the engineer with a very stable, accurate voltage with ultra low noise and very high Power Supply Rejection Ratio (PSRR) suitable for RF applications. In order to optimize performance for battery operated portable applications, the NCV8570 employs an advanced BiCMOS process to combine the benefits of low noise and superior dynamic performance of bipolar elements with very low ground current consumption at full loads offered by CMOS.

Furthermore, in order to provide a small footprint for space-conscious applications, the NCV8570 is stable with small, low value capacitors and is available in very small DFN6 2x2.2 and TSOP-5 packages.

### Features

- Output Voltage Options:
  - ◆ 1.8 V, 2.5 V, 2.75 V, 2.8 V, 3.0 V, 3.3 V
  - ◆ Contact Factory for Other Voltage Options
- Output Current Limit 200 mA
- Ultra Low Noise (typ 15  $\mu\text{V}_{\text{rms}}$ )
- Very High PSRR (typ 80 dB)
- Stable with Ceramic Output Capacitors as low as 1  $\mu\text{F}$
- Low Sleep Mode Current (max 1  $\mu\text{A}$ )
- Active Discharge Circuit
- Current Limit Protection
- Thermal Shutdown Protection
- NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These are Pb-Free Devices

### Typical Applications

- Satellite and HD Radio
- Noise Sensitive Applications (Video, Audio)
- Analog Power Supplies
- Portable/Built-in DVD Entertainment Systems
- GPS

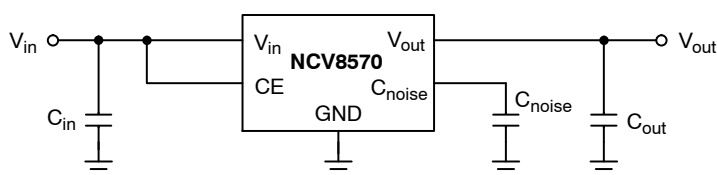


Figure 1. Typical Application Schematic



ON Semiconductor®

<http://onsemi.com>

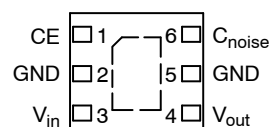


DFN6  
MN SUFFIX  
CASE 506BA

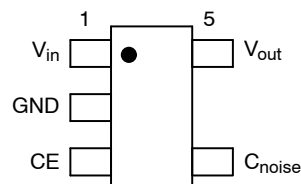


TSOP-5  
SN SUFFIX  
CASE 483

### PIN ASSIGNMENTS

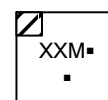


DFN6  
(Top View)



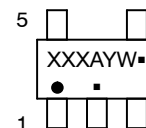
TSOP-5  
(Top View)

### MARKING DIAGRAMS



XX = Specific Device Code  
M = Date Code  
■ = Pb-Free Package

(Note: Microdot may be in either location)



XXX = Specific Device Code  
A = Assembly Location  
Y = Year  
W = Work Week  
■ = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.

## NCV8570

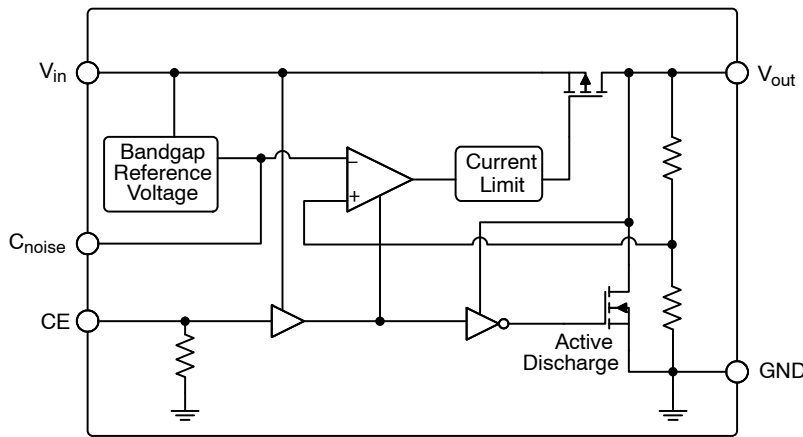


Figure 2. Simplified Block Diagram

### PIN FUNCTION DESCRIPTION

| Pin No.<br>DFN6 | TSOP-5 | Pin Name    | Description                                                                                                                                                                                                                          |
|-----------------|--------|-------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 1               | 3      | CE          | Chip Enable: This pin allows on/off control of the regulator. To disable the device, connect to GND. If this function is not in use, connect to $V_{in}$ . Internal 5 M $\Omega$ Pull Down resistor is connected between CE and GND. |
| 2, 5, EPAD      | 2      | GND         | Power Supply Ground (Pins are fused for the DFN package)                                                                                                                                                                             |
| 3               | 1      | $V_{in}$    | Power Supply Input Voltage                                                                                                                                                                                                           |
| 4               | 5      | $V_{out}$   | Regulated Output Voltage                                                                                                                                                                                                             |
| 6               | 4      | $C_{noise}$ | Noise reduction pin. (Connect 100 nF or 10 nF capacitor to GND)                                                                                                                                                                      |

### MAXIMUM RATINGS

| Rating                                | Symbol       | Value                      | Unit         |
|---------------------------------------|--------------|----------------------------|--------------|
| Input Voltage (Note 1)                | $V_{in}$     | -0.3 V to 6 V              | V            |
| Chip Enable Voltage                   | $V_{CE}$     | -0.3 V to $V_{in} + 0.3$ V | V            |
| Noise Reduction Voltage               | $V_{Cnoise}$ | -0.3 V to $V_{in} + 0.3$ V | V            |
| Output Voltage                        | $V_{out}$    | -0.3 V to $V_{in} + 0.3$ V | V            |
| Maximum Junction Temperature (Note 1) | $T_{J(max)}$ | 150                        | $^{\circ}$ C |
| Storage Temperature Range             | $T_{STG}$    | -55 to 150                 | $^{\circ}$ C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

NOTE: This device series contains ESD protection and exceeds the following tests:

Human Body Model 2000 V per MIL-STD-883, Method 3015

Machine Model Method 200 V

This device series meets or exceeds AEC Q100 standard.

### THERMAL CHARACTERISTICS

| Rating                                                                                          | Symbol          | Value      | Unit           |
|-------------------------------------------------------------------------------------------------|-----------------|------------|----------------|
| Package Thermal Resistance, DFN6: (Note 1)<br>Junction-to-Lead (pin 2)<br>Junction-to-Ambient   | $R_{\theta JA}$ | 37<br>120  | $^{\circ}$ C/W |
| Package Thermal Resistance, TSOP-5: (Note 1)<br>Junction-to-Lead (pin 5)<br>Junction-to-Ambient | $R_{\theta JA}$ | 109<br>220 | $^{\circ}$ C/W |

1. Refer to ELECTRICAL CHARACTERISTICS and APPLICATION INFORMATION for Safe Operating Area

# ELECTRICAL CHARACTERISTICS

( $V_{in} = V_{out} + 0.5\text{ V}$ ,  $V_{CE} = 1.2\text{ V}$ ,  $C_{in} = 0.1\text{ }\mu\text{F}$ ,  $C_{out} = 1\text{ }\mu\text{F}$ ,  $C_{noise} = 10\text{ nF}$ ,  $T_A = -40^\circ\text{C}$  to  $85^\circ\text{C}$ , unless otherwise specified (Note 2))

| Characteristic                | Test Conditions                                                                                                                                                                                | Symbol       | Min                                                          | Typ                             | Max                                                          | Unit          |
|-------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------|--------------------------------------------------------------|---------------------------------|--------------------------------------------------------------|---------------|
| <b>REGULATOR OUTPUT</b>       |                                                                                                                                                                                                |              |                                                              |                                 |                                                              |               |
| Input Voltage                 |                                                                                                                                                                                                | $V_{in}$     | 2.5                                                          | –                               | 5.5                                                          | V             |
| Output Voltage (Note 3)       | 1.8 V<br>2.5 V<br>2.75 V<br>2.8 V<br>3.0 V<br>3.3 V<br>$V_{in} = (V_{out} + 0.5\text{ V})$ to 5.5 V<br>$I_{out} = 1\text{ mA}$                                                                 | $V_{out}$    | 1.764<br>2.450<br>2.695<br>2.744<br>2.940<br>3.234<br>(–2%)  | –<br>–<br>–<br>–<br>–<br>–      | 1.836<br>2.550<br>2.805<br>2.856<br>3.060<br>3.366<br>(+2%)  | V             |
| Output Voltage (Note 3)       | 1.8 V<br>2.5 V<br>2.75 V<br>2.8 V<br>3.0 V<br>3.3 V<br>$V_{in} = (V_{out} + 0.5\text{ V})$ to 5.5 V<br>$I_{out} = 1\text{ mA}$ to 200 mA                                                       | $V_{out}$    | 1.746<br>2.425<br>2.6675<br>2.716<br>2.910<br>3.201<br>(–3%) | –<br>–<br>–<br>–<br>–<br>–      | 1.854<br>2.575<br>2.8325<br>2.884<br>3.090<br>3.399<br>(+3%) | V             |
| Power Supply Ripple Rejection | $V_{in} = V_{out} + 1.0\text{ V} + 0.5\text{ V}_{p-p}$<br>$I_{out} = 1\text{ mA}$ to 150 mA<br>$C_{noise} = 100\text{ nF}$<br>$f = 120\text{ Hz}$<br>$f = 1\text{ kHz}$<br>$f = 10\text{ kHz}$ | PSRR         | –<br>–<br>–                                                  | 80<br>80<br>65                  | –<br>–<br>–                                                  | dB            |
| Line Regulation               | $V_{in} = (V_{out} + 0.5\text{ V})$ to 5.5 V, $I_{out} = 1\text{ mA}$                                                                                                                          | $Reg_{line}$ | –0.2                                                         | –                               | 0.2                                                          | %/V           |
| Load Regulation               | $I_{out} = 1\text{ mA}$ to 200 mA                                                                                                                                                              | $Reg_{load}$ | –                                                            | 12                              | 25                                                           | mV            |
| Output Noise Voltage          | $f = 10\text{ Hz}$ to 100 kHz<br>$I_{out} = 1\text{ mA}$ to 150 mA<br>$C_{noise} = 100\text{ nF}$<br>$C_{noise} = 10\text{ nF}$                                                                | $V_n$        | –<br>–                                                       | 15<br>20                        | –<br>–                                                       | $\mu V_{rms}$ |
| Output Current Limit          | $V_{out} = V_{out(nom)} - 0.1\text{ V}$                                                                                                                                                        | $I_{LIM}$    | 200                                                          | 310                             | 470                                                          | mA            |
| Output Short Circuit Current  | $V_{out} = 0\text{ V}$                                                                                                                                                                         | $I_{SC}$     | 210                                                          | 320                             | 490                                                          | mA            |
| Dropout Voltage (Note 4, 5)   | 2.5 V<br>2.75 V<br>2.8 V<br>3.0 V<br>3.3 V<br>$I_{out} = 150\text{ mA}$                                                                                                                        | $V_{DO}$     | –<br>–<br>–<br>–<br>–                                        | 105<br>105<br>105<br>100<br>100 | 155<br>155<br>155<br>150<br>150                              | mV            |
| Dropout Voltage (Note 6)      | 2.5 V<br>2.75 V<br>2.8 V<br>3.0 V<br>3.3 V<br>$I_{out} = 200\text{ mA}$                                                                                                                        | $V_{DO}$     | –<br>–<br>–<br>–<br>–                                        | 170<br>150<br>150<br>140<br>130 | 215<br>205<br>205<br>200<br>200                              | mV            |

## GENERAL

|                                      |                                                      |           |        |           |           |                  |
|--------------------------------------|------------------------------------------------------|-----------|--------|-----------|-----------|------------------|
| Ground Current                       | $I_{out} = 1\text{ mA}$<br>$I_{out} = 200\text{ mA}$ | $I_{GND}$ | –<br>– | 70<br>110 | 90<br>220 | $\mu\text{A}$    |
| Disable Current                      | $V_{CE} = 0\text{ V}$                                | $I_{DIS}$ | –      | 0.1       | 1         | $\mu\text{A}$    |
| Thermal Shutdown Threshold (Note 4)  |                                                      | $T_{SD}$  | –      | 150       | –         | $^\circ\text{C}$ |
| Thermal Shutdown Hysteresis (Note 4) |                                                      | $T_{SH}$  | –      | 20        | –         | $^\circ\text{C}$ |

## CHIP ENABLE

|                                        |             |              |          |        |          |           |
|----------------------------------------|-------------|--------------|----------|--------|----------|-----------|
| Input Threshold                        | Low<br>High | $V_{th(CE)}$ | –<br>1.2 | –<br>– | 0.4<br>– | V         |
| Internal Pull-Down Resistance (Note 7) |             | $R_{PD(CE)}$ | 2.5      | 5      | 10       | $M\Omega$ |

## TIMING

|               |                                                                                                 |           |        |            |        |               |
|---------------|-------------------------------------------------------------------------------------------------|-----------|--------|------------|--------|---------------|
| Turn-on Time  | $I_{out} = 150\text{ mA}$<br>$C_{noise} = 10\text{ nF}$<br>$C_{noise} = 100\text{ nF}$          | $t_{on}$  | –<br>– | 0.4<br>4   | –<br>– | ms            |
| Turn-off Time | $C_{noise} = 10\text{ nF}/100\text{ nF}$<br>$I_{out} = 1\text{ mA}$<br>$I_{out} = 10\text{ mA}$ | $t_{off}$ | –<br>– | 800<br>200 | –<br>– | $\mu\text{s}$ |

- Performance guaranteed over the indicated operating temperature range by design and/or characterization, production tested at  $T_J = T_A = 25^\circ\text{C}$ . Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible.
- Contact factory for other voltage options.
- Guaranteed by design and characterization.
- Characterized when output voltage falls 100 mV below the regulated voltage at  $V_{in} = V_{out} + 1\text{ V}$  if  $V_{out} < 2.5\text{ V}$ , then  $V_{DO} = V_{in} - V_{out}$  at  $V_{in} = 2.5\text{ V}$ .
- Measured when output voltage falls 100 mV below the regulated voltage at  $V_{in} = V_{out} + 0.5\text{ V}$  if  $V_{out} < 2.5\text{ V}$ , then  $V_{DO} = V_{in} - V_{out}$  at  $V_{in} = 2.5\text{ V}$ .
- Expected to disable device when CE pin is floating.

TYPICAL CHARACTERISTICS

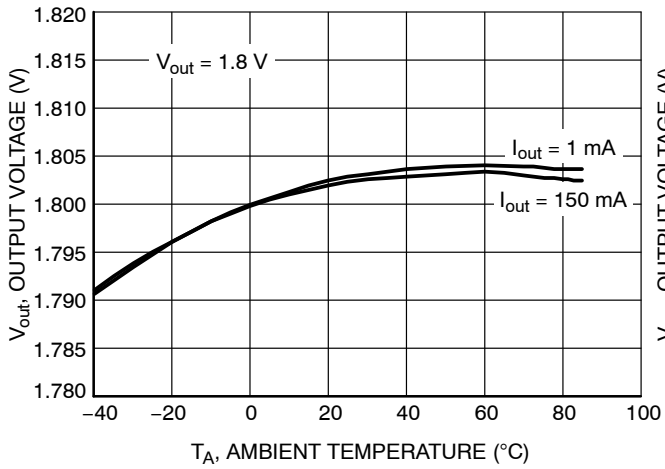


Figure 3. Output Voltage vs. Temperature  
( $V_{out} = 1.8\text{ V}$ )

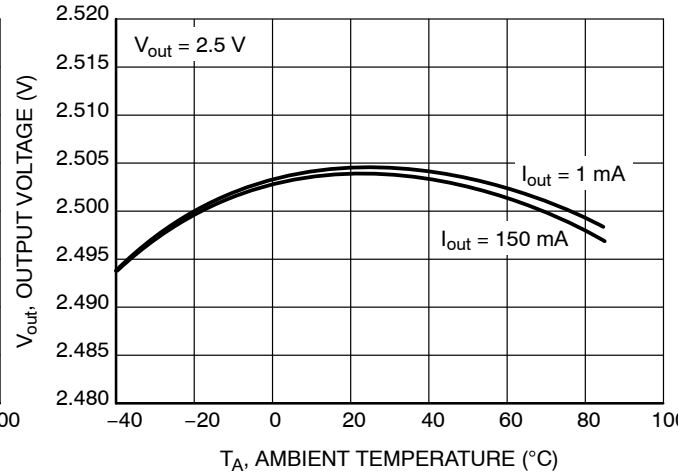


Figure 4. Output Voltage vs. Temperature  
( $V_{out} = 2.5\text{ V}$ )

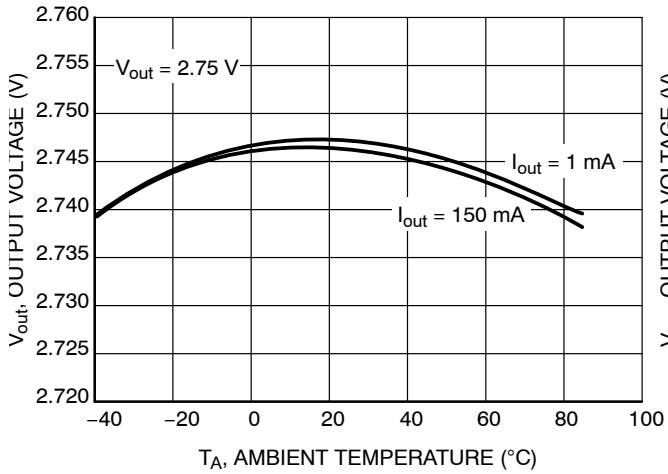


Figure 5. Output Voltage vs. Temperature  
( $V_{out} = 2.75\text{ V}$ )

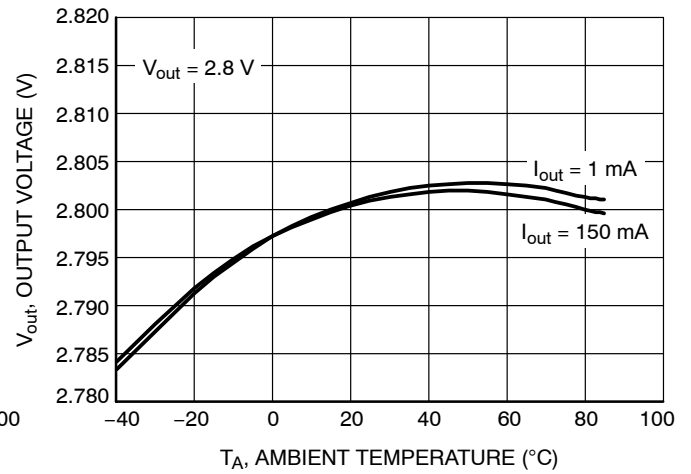


Figure 6. Output Voltage vs. Temperature  
( $V_{out} = 2.8\text{ V}$ )

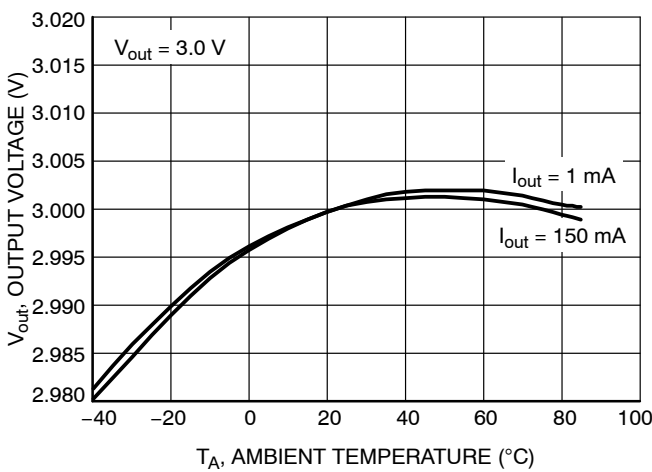


Figure 7. Output Voltage vs. Temperature  
( $V_{out} = 3.0\text{ V}$ )

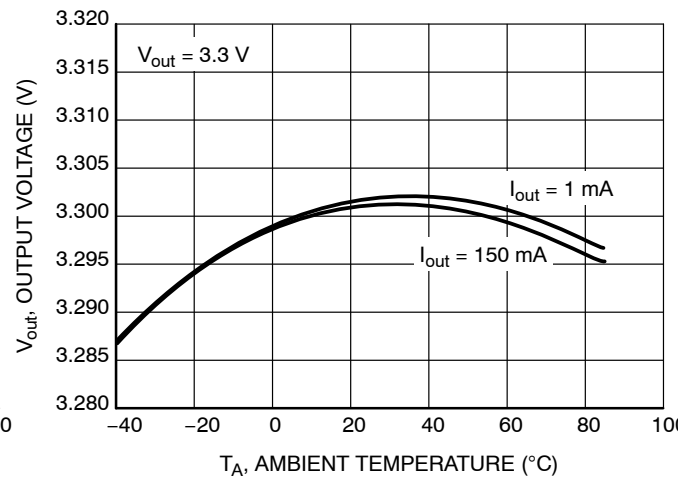


Figure 8. Output Voltage vs. Temperature  
( $V_{out} = 3.3\text{ V}$ )

TYPICAL CHARACTERISTICS

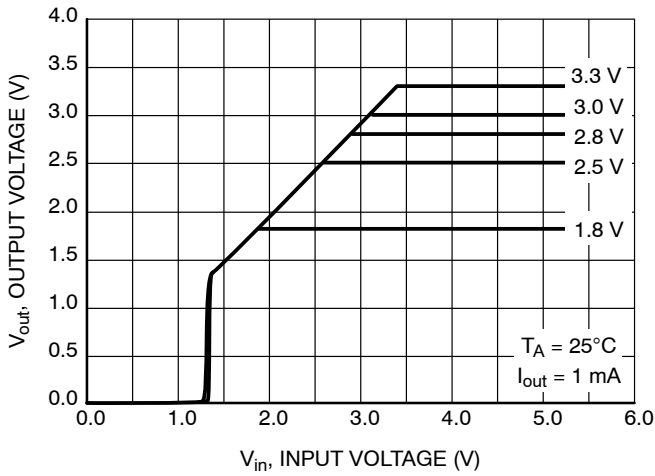


Figure 9. Output Voltage vs. Input Voltage

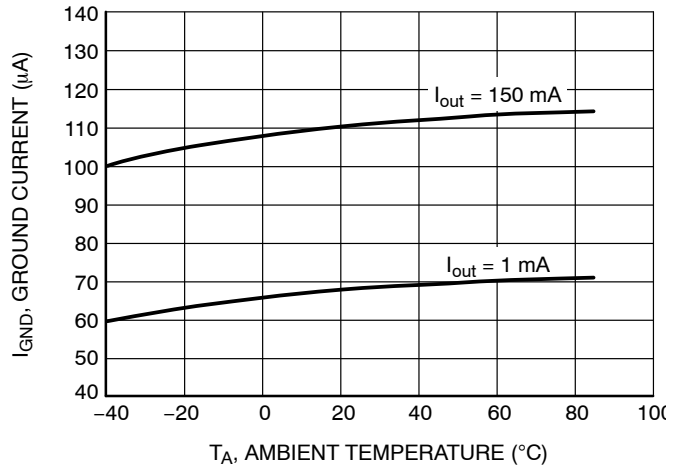


Figure 10. Ground Current vs. Temperature

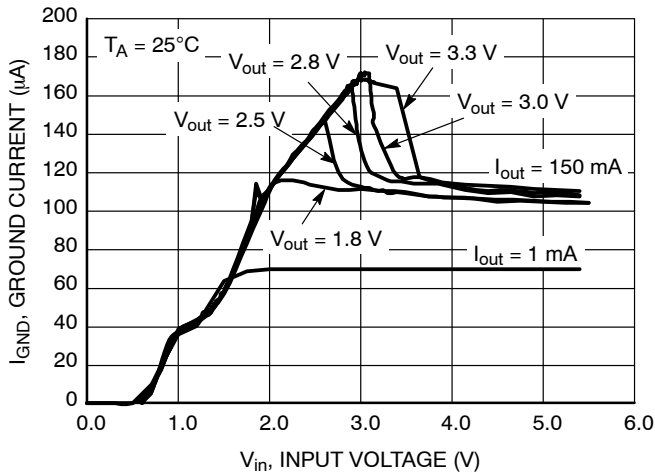


Figure 11. Ground Current vs. Input Voltage

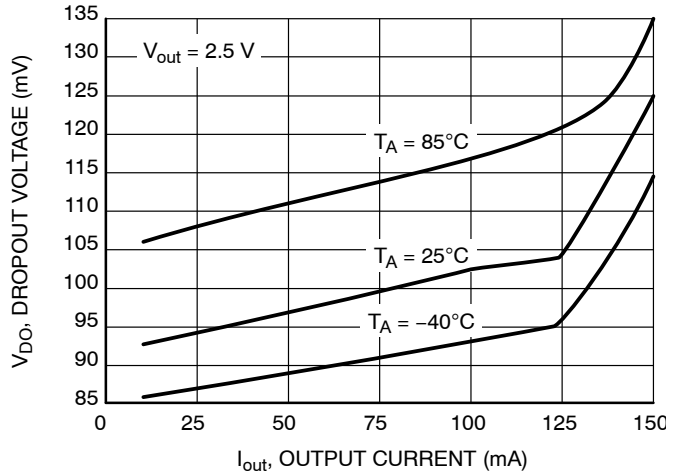


Figure 12. Dropout Voltage vs. Output Current

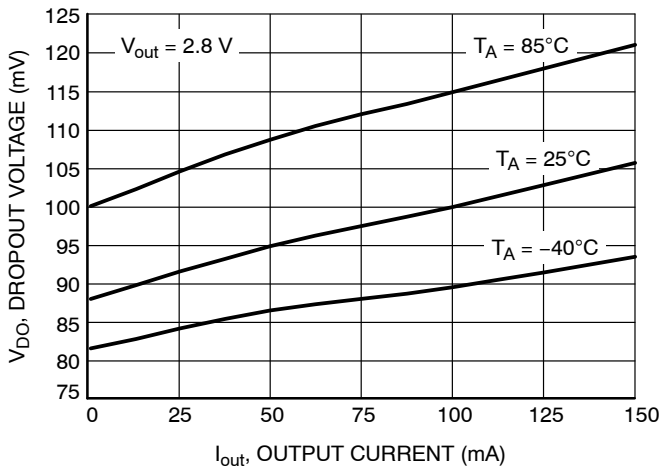


Figure 13. Dropout Voltage vs. Output Current

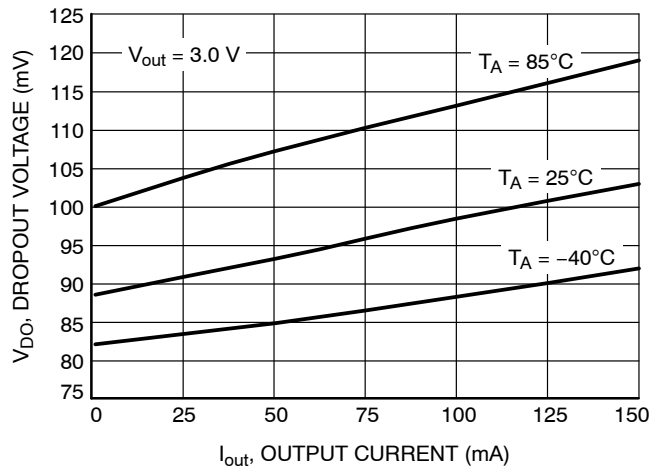


Figure 14. Dropout Voltage vs. Output Current

TYPICAL CHARACTERISTICS

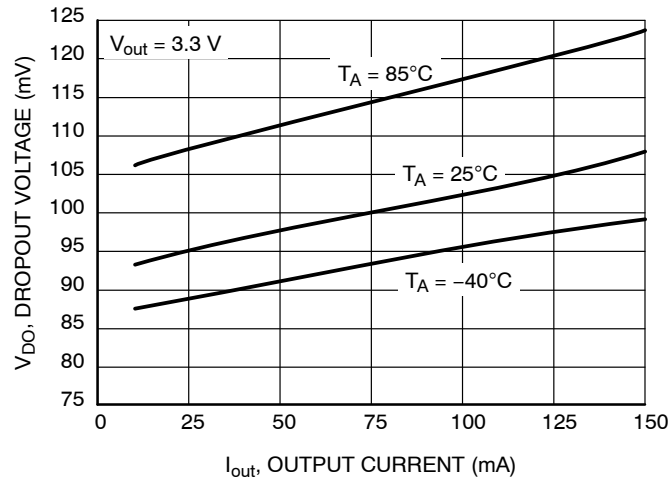


Figure 15. Dropout Voltage vs. Output Current

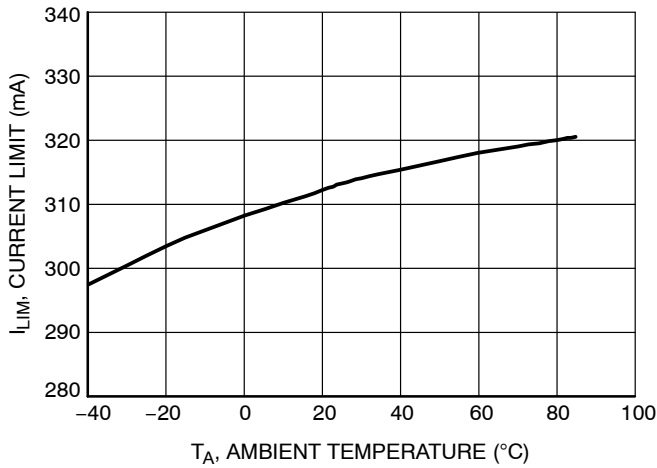


Figure 16. Current Limit vs. Temperature

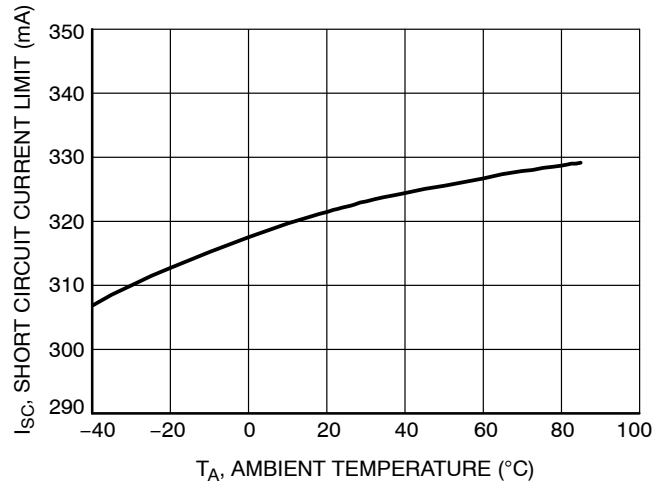


Figure 17. Short Circuit Current vs. Temperature

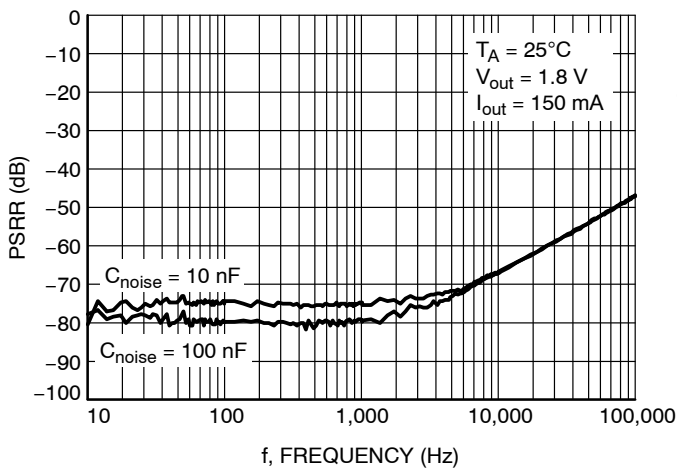


Figure 18. PSRR vs. Frequency

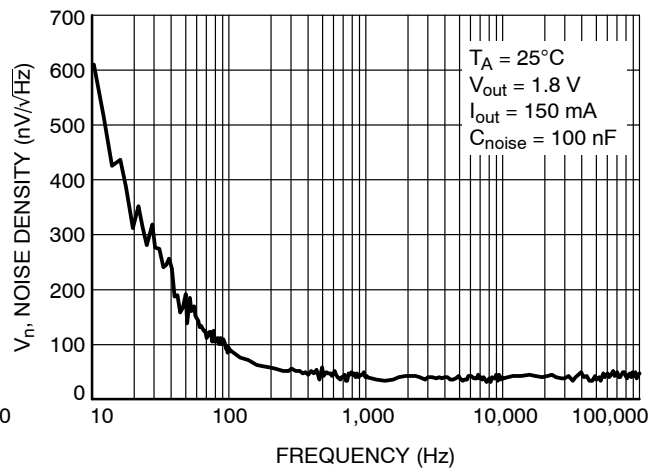


Figure 19. Noise Density vs. Frequency

TYPICAL CHARACTERISTICS

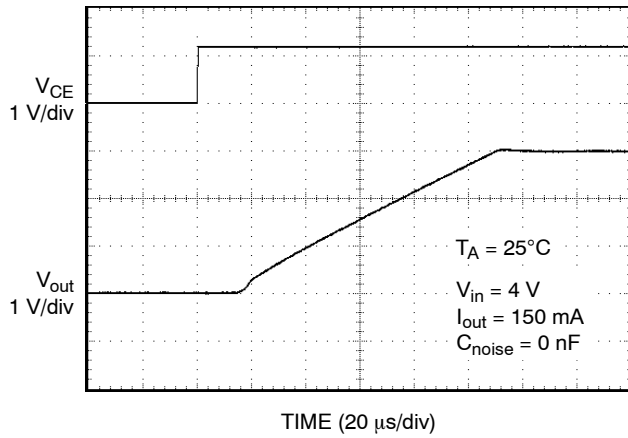


Figure 20. Enable Voltage and Output Voltage vs. Time (Start-Up)

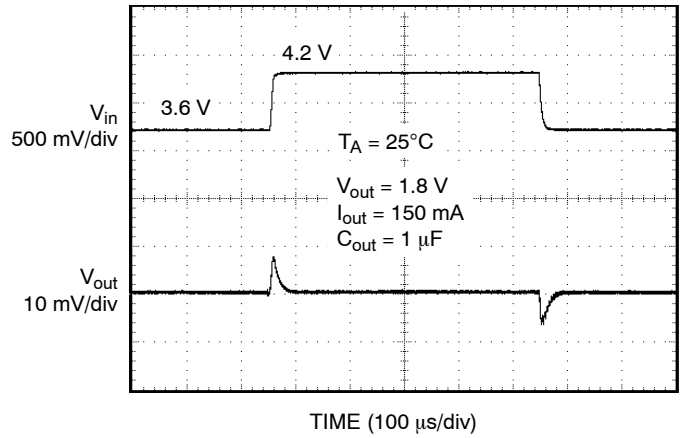


Figure 21. Line Transient

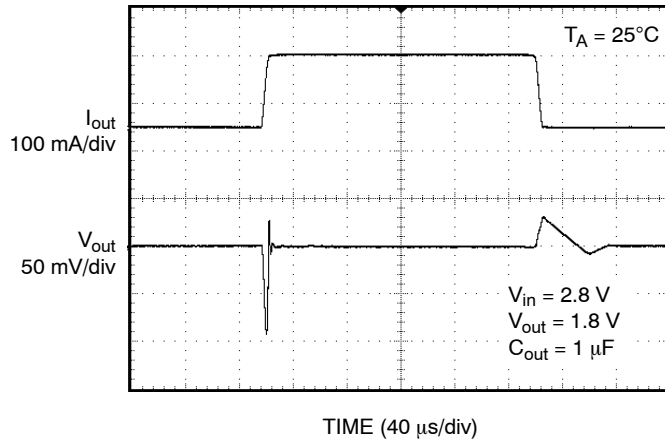


Figure 22. Load Transient

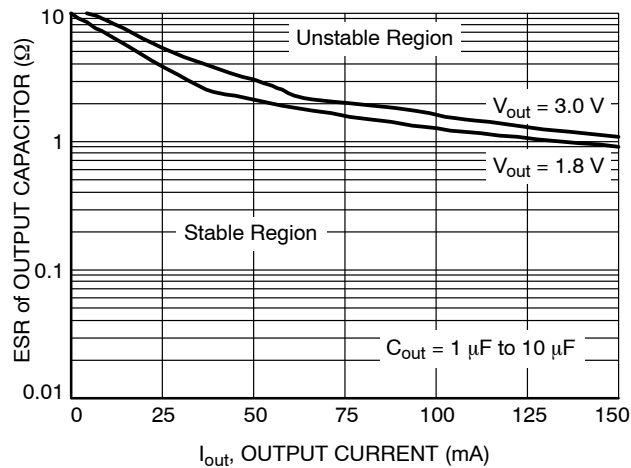


Figure 23. Output Capacitor ESR vs. Output Current

## APPLICATION INFORMATION

**General**

The NCV8570 is a 200 mA (current limited) linear regulator with a logic input for on/off control for the high speed turn-off output voltage.

Access to the major contributor of noise within the integrated circuit is provided as the focus for noise reduction within the linear regulator system.

**Power Up/Down**

During power up, the NCV8570 maintains a high impedance output ( $V_{out}$ ) until sufficient voltage is present on  $V_{in}$  to power the internal bandgap reference voltage. When sufficient voltage is supplied (approx 1.2 V),  $V_{out}$  will start to turn on (assume CE shorted to  $V_{in}$ ), linearly increasing until the output regulation voltage has been reached.

Active discharge circuitry has been implemented to insure a fast turn off time. Then CE goes low, the active discharge transistor turns on creating a fast discharge of the output voltage. Power to drive this circuitry is drawn from the output node. This is to maintain the lowest quiescent current when in the sleep mode ( $V_{CE} = 0.4$  V). This circuitry subsequently turns off when the output voltage discharges.

**CE (chip enable)**

The enable function is controlled by the logic pin CE. The voltage threshold of this pin is set between 0.4 V and 1.2 V. A voltage lower than 0.4 V guarantees the device is off. A voltage higher than 1.2 V guarantees the device is on. The NCV8570 enters a sleep mode when in the off state drawing less than 1  $\mu$ A of quiescent current.

The device can be used as a simple regulator without use of the chip enable feature by tying the CE pin to the  $V_{in}$  pin.

**Current Limit**

Output Current is internally limited within the IC to a minimum of 200 mA. The design is set to a higher value to allow for variation in processing and the temperature coefficient of the parameter. The NCV8570 will source this amount of current measured with a voltage 100 mV lower than the typical operating output voltage.

The specification for short circuit current limit (@  $V_{out} = 0$  V) is specified at 320 mA (typ). There is no additional circuitry to lower the current limit at low output voltages. This number is provided for informational purposes only.

**Output Capacitor**

The NCV8570 has been designed to work with low ESR ceramic capacitors. There is no ESR lower limit for stability for the recommended 1  $\mu$ F output capacitor. Stable region for Output capacitor ESR vs Output Current is shown in Figure 23.

Typical characteristics were measured with Murata ceramic capacitors. GRM219R71E105K (1  $\mu$ F, 25 V, X7R, 0805) and GRM21BR71A106K (10  $\mu$ F, 10 V, X7R, 0805).

**Output Noise**

The main contributor for noise present on the output pin  $V_{out}$  is the reference voltage node. This is because any noise which is generated at this node will be subsequently amplified through the error amplifier and the PMOS pass device. Access to the reference voltage node is supplied directly through the  $C_{noise}$  pin. Noise can be reduced from a typical value of 20  $\mu$ V<sub>rms</sub> by using 10 nF to 15  $\mu$ V<sub>rms</sub> by using a 100 nF from the  $C_{noise}$  pin to ground.

A bypass capacitor is recommended for good noise performance and better load transient response.

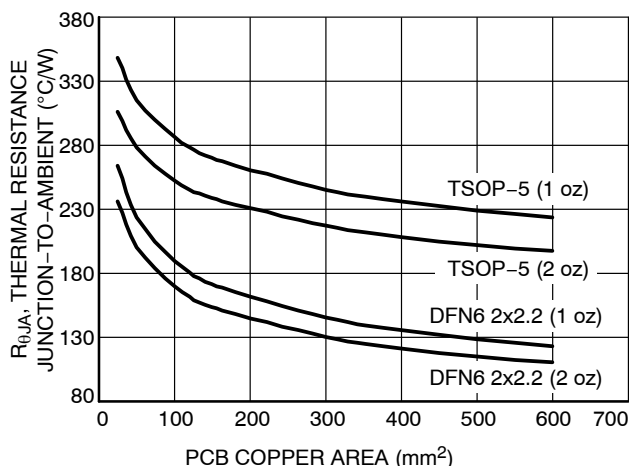
**Thermal Shutdown**

When the die temperature exceeds the Thermal Shutdown threshold, a Thermal Shutdown (TSD) event is detected and the output ( $V_{out}$ ) is turned off. There is no effect from the active discharge circuitry. The IC will remain in this state until the die temperature moves below the shutdown threshold (150°C typical) minus the hysteresis factor (20°C typical).

This feature provides protection from a catastrophic device failure due to accidental overheating. It is not intended to be used as a substitute for proper heat sinking. The maximum device power dissipation can be calculated by:

$$P_D = \frac{T_J - T_A}{R_{\theta JA}}$$

Thermal resistance value versus copper area and package is shown in Figure 24.



**Figure 24.  $R_{\theta JA}$  vs. PCB Copper Area**

(TSOP-5 for comparison only)



# NCV8570

## ORDERING INFORMATION

| Device*         | Nominal Output Voltage | Marking | Package                    | Shipping†          |
|-----------------|------------------------|---------|----------------------------|--------------------|
| NCV8570MN180R2G | 1.8 V                  | MT      | DFN6<br>2x2.2<br>(Pb-Free) | 3000 / Tape & Reel |
| NCV8570MN250R2G | 2.5 V                  | MU      |                            |                    |
| NCV8570MN275R2G | 2.75 V                 | MV      |                            |                    |
| NCV8570MN280R2G | 2.8 V                  | MW      |                            |                    |
| NCV8570MN300R2G | 3.0 V                  | MX      |                            |                    |
| NCV8570MN330R2G | 3.3 V                  | MY      |                            |                    |
| NCV8570SN18T1G  | 1.8 V                  | ACV     | TSOP-5<br>(Pb-Free)        | 3000 / Tape & Reel |
| NCV8570SN25T1G  | 2.5 V                  | ACW     |                            |                    |
| NCV8570SN275T1G | 2.75 V                 | ACX     |                            |                    |
| NCV8570SN28T1G  | 2.8 V                  | ACY     |                            |                    |
| NCV8570SN30T1G  | 3.0 V                  | ACZ     |                            |                    |
| NCV8570SN33T1G  | 3.3 V                  | AC2     |                            |                    |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

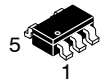
\*NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

The products described herein (NCV8570), may be covered by one or more U.S. patents.

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

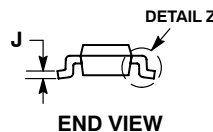
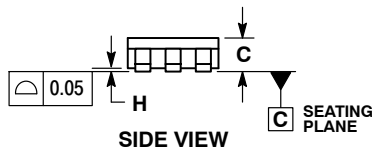
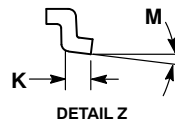
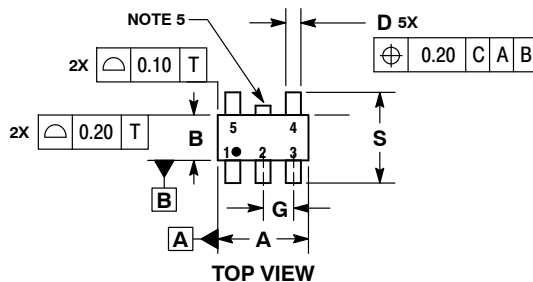
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SCALE 2:1

### TSOP-5 CASE 483 ISSUE N

DATE 12 AUG 2020

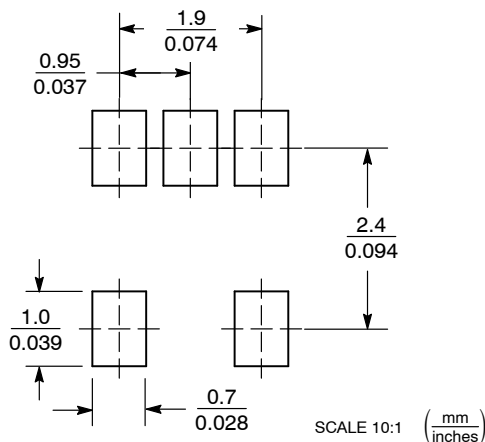


#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION A.
5. OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

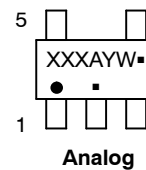
| DIM | MILLIMETERS |      |
|-----|-------------|------|
|     | MIN         | MAX  |
| A   | 2.85        | 3.15 |
| B   | 1.35        | 1.65 |
| C   | 0.90        | 1.10 |
| D   | 0.25        | 0.50 |
| G   | 0.95 BSC    |      |
| H   | 0.01        | 0.10 |
| J   | 0.10        | 0.26 |
| K   | 0.20        | 0.60 |
| M   | 0°          | 10°  |
| S   | 2.50        | 3.00 |

#### SOLDERING FOOTPRINT\*

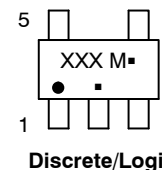


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### GENERIC MARKING DIAGRAM\*



Analog



Discrete/Logic

XXX = Specific Device Code  
 A = Assembly Location  
 Y = Year  
 W = Work Week  
 ■ = Pb-Free Package

XXX = Specific Device Code  
 M = Date Code  
 ■ = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

|                  |             |                                                                                                                                                                                  |
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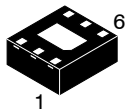
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# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

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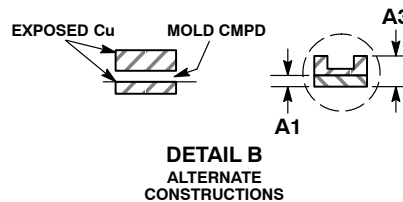
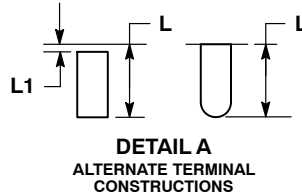
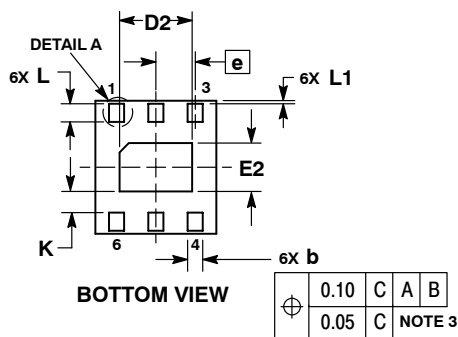
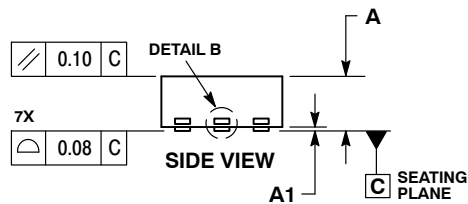
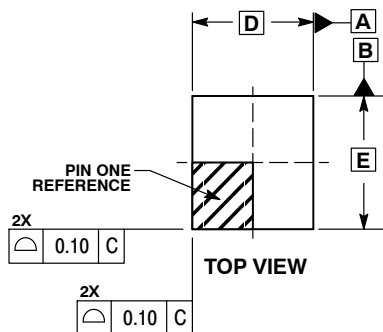
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SCALE 4:1

DFN6, 2x2.2, 0.65P  
CASE 506BA-01  
ISSUE A

DATE 07 JUL 2008

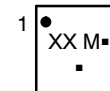


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

| MILLIMETERS |          |      |
|-------------|----------|------|
| DIM         | MIN      | MAX  |
| A           | 0.80     | 1.00 |
| A1          | 0.00     | 0.05 |
| b           | 0.20     | 0.30 |
| D           | 2.00 BSC |      |
| D2          | 1.10     | 1.30 |
| E           | 2.20 BSC |      |
| E2          | 0.70     | 0.90 |
| e           | 0.65 BSC |      |
| K           | 0.20     | ---  |
| L           | 0.25     | 0.35 |
| L1          | 0.00     | 0.10 |

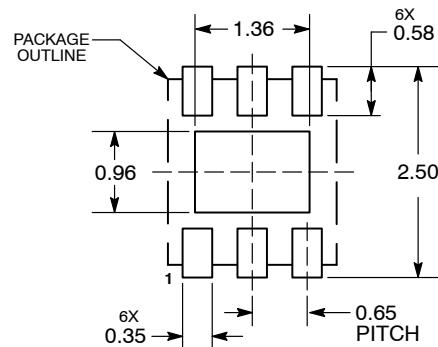
### GENERIC MARKING DIAGRAM\*



XX = Specific Device Code  
M = Date Code  
▪ = Pb-Free Device

\*This information is generic. Please refer to device data sheet for actual part marking.  
Pb-Free indicator, "G" or microdot "▪", may or may not be present.

### SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

|                  |                           |                                                                                                                                                                                     |
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